

1

2

3

4

A

B

C

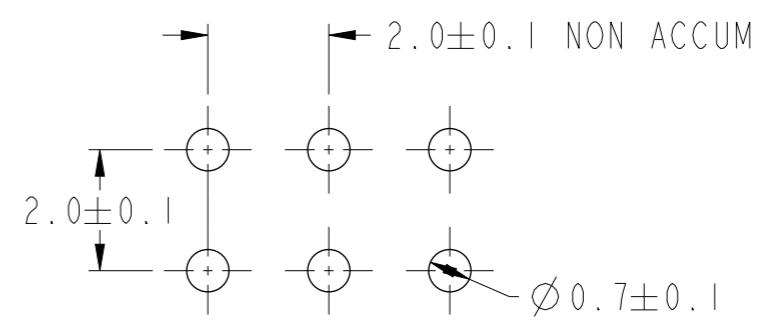
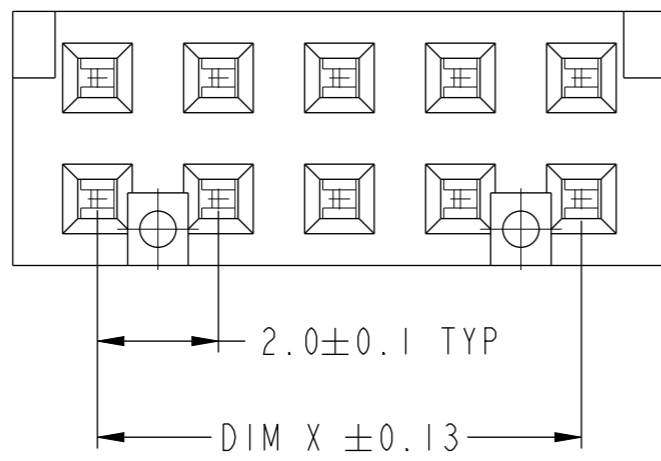
D

A

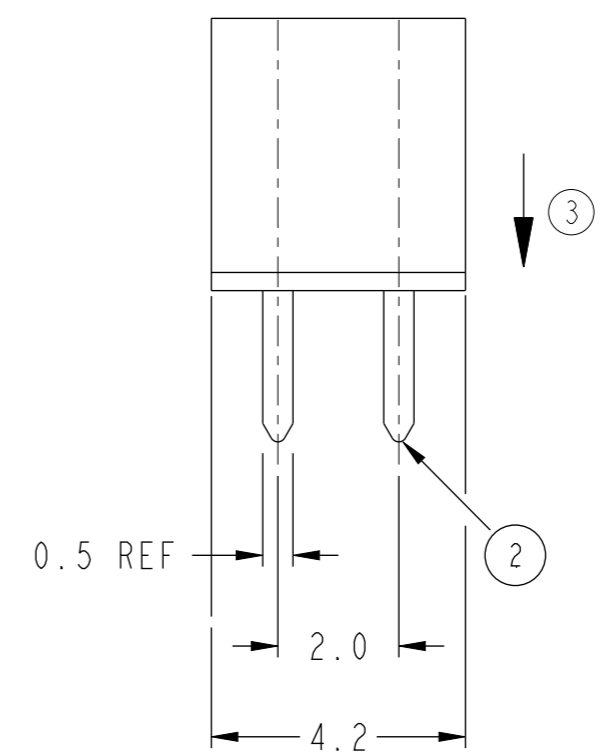
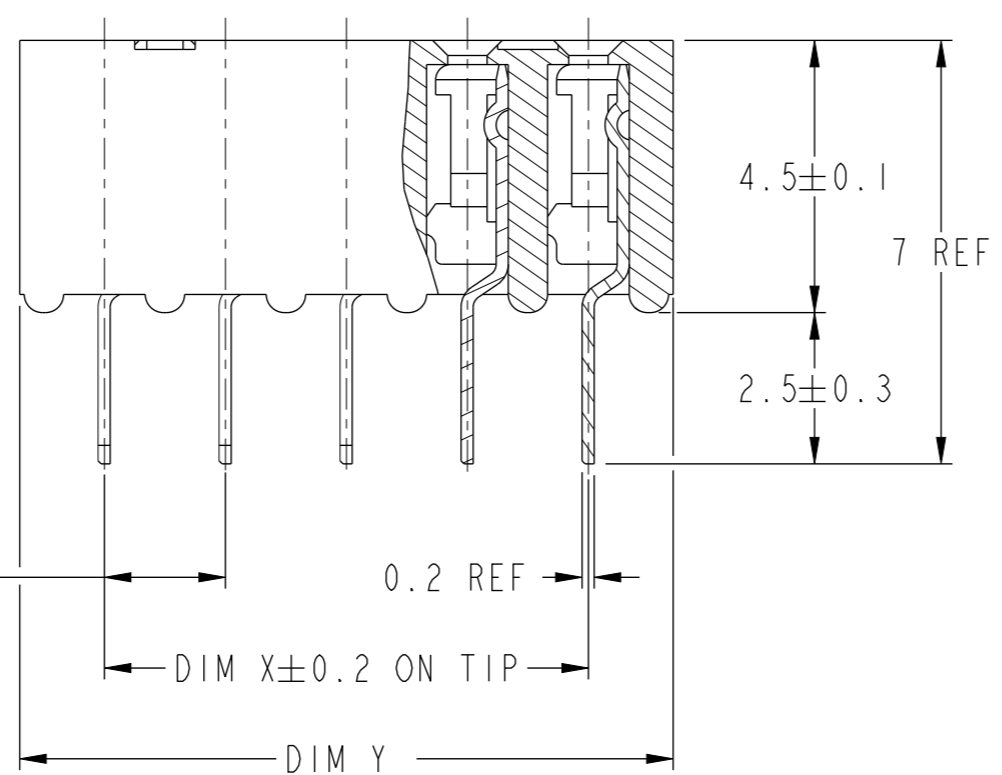
B

C

D



PC BOARD THK: 0.9 TO 1.3 FOR PIP; 1.57±0.13 FOR WAVE SOLDERING.
RECOMMENDED MOUNTING HOLE LAYOUT



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spec ref	*	dr	Andrew Yong	2010/10/22	projection	MM	size	A3	scale	5:1		
tolerance std	ISO 406 ISO 1101	eng	Yuan-Yuan Bao	2022/01/04			ecn no	ELX-N-43425-1				
surface	ISO 1302	chr	-	apppr			Tim Yao	2022/01/04	rel level	Released		
		linear	0.X	±-	Amphenol FCI MINITEK II VCC (HTP)			dwg no	63453		rev	K
		angular	0°	±°				www.fci.com	cat. no.	Product - Customer Drw		sheet 1 of 2

Creo File:ELX-WC-A3C.REV F.2020-12-21

2

3

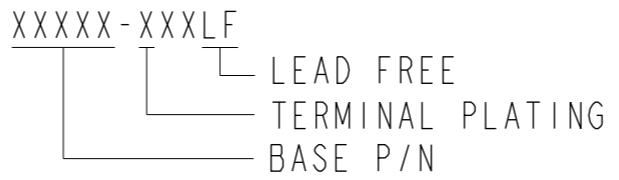
PDS: Rev :K

STATUS:Released

Printed: Jan 06, 2022

PRODUCT NO	PRODUCT NO	POS	DIM X	DIM Y
63453-X04	63453-X04LF (8)	2X2	2	4.8
X06	X06LF ↑	2X3	4	6.8
X08	X08LF	2X4	6	8.8
X10	X10LF	2X5	8	10.8
X12	X12LF	2X6	10	12.8
X14	X14LF	2X7	12	14.8
X16	X16LF	2X8	14	16.8
X18	X18LF	2X9	16	18.8
X20	X20LF	2X10	18	20.8
X22	X22LF	2X11	20	22.8
X24	X24LF	2X12	22	24.8
X26	X26LF	2X13	24	26.8
X28	X28LF	2X14	26	28.8
X30	X30LF	2X15	28	30.8
X32	X32LF	2X16	30	32.8
X34	X34LF	2X17	32	34.8
X36	X36LF	2X18	34	36.8
X38	X38LF	2X19	36	38.8
X40	X40LF	2X20	38	40.8
X42	X42LF	2X21	40	42.8
X44	X44LF	2X22	42	44.8
X46	X46LF	2X23	44	46.8
X48	X48LF ↓	2X24	46	48.8
X50	X50LF (8)	2X25	48	50.8

PART NUMBER INFORMATION



PLATING	DESCRIPTION (CONTACT AREA)
0	0.2 μm Au
1	0.76 μm Au
2	UNASSIGNED
3	0.38 μm Au
4	2.54 μm Matte Tin

NOTES:

- MATERIAL :
BODY : HIGH TEMPERATURE THERMAL PLASTIC, UL 94V-0, BLACK
TERMINAL : PHOSPHOR BRONZE
- CUT SURFACE IS UNPLATED
- TERMINAL RETENTION FORCE 0.5 Kg MIN
- TOLERANCE UNLESS OTHERWISE NOTED ±0.25
- 63453-XXX PACKAGING IN TUBE WITHOUT PLASTIC CAP.
63453-XXXTR PACKAGING IN TAPE AND REEL WITH PLASTIC CAP.
63453-XXXTRN PACKAGING IN TAPE AND REEL WITHOUT PLASTIC CAP.
A PICK-UP CAP IS PROVIDED IN THE CENTRE OF THE PRODUCT (SEE FIG.1) FOR PICK AND PLACE APPLICATION.
- THE HOUSING WILL WITHSTAND EXPOSURE TO 255° C PEAK TEMPERATURE FOR 10 SECONDS IN A CONVECTION, INFRA-RED OR VAPOR PHASE REFLOW OVEN.
- THE HOUSING WILL WITHSTAND EXPOSURE TO 260°C PEAK TEMPERATURE FOR 10 SECONDS IN A WAVE SOLDER APPLICATION WITH A 1.57MM MINIMUM THICK CIRCUIT BOARD.
- THIS PRODUCT MEETS EUROPEAN UNION DIRECTIVES AND OTHER COUNTRY REGULATIONS AS DESCRIBED IN GS-22-008.

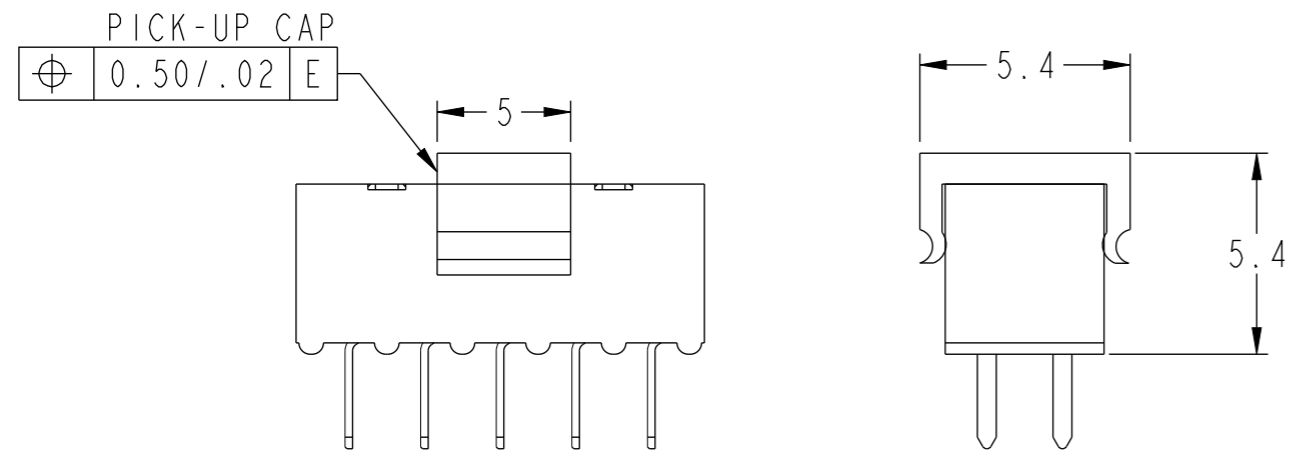


FIG. 1

dr	Andrew Yong	2010/10/22	projection	MM	size	A3	scale	13:1
eng	Yuan-Yuan Bao	2022/01/04			ecn no	ELX-N-43425-1		
chr	-	-			rel level	Released		
appr	Tim Yao	2022/01/04	product family	-	rel level	Released		
Amphenol FCI		MINITEK II		dwg no	63453		rev	K
www.fci.com		cat. no.	-	Product - Customer Drw			sheet 2 of 2	

Amphenol FCI

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